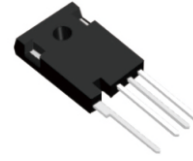


## CSMFP4OT040-HF

**N-Channel**  
**RoHS Device**  
**Halogen Free**



### Features

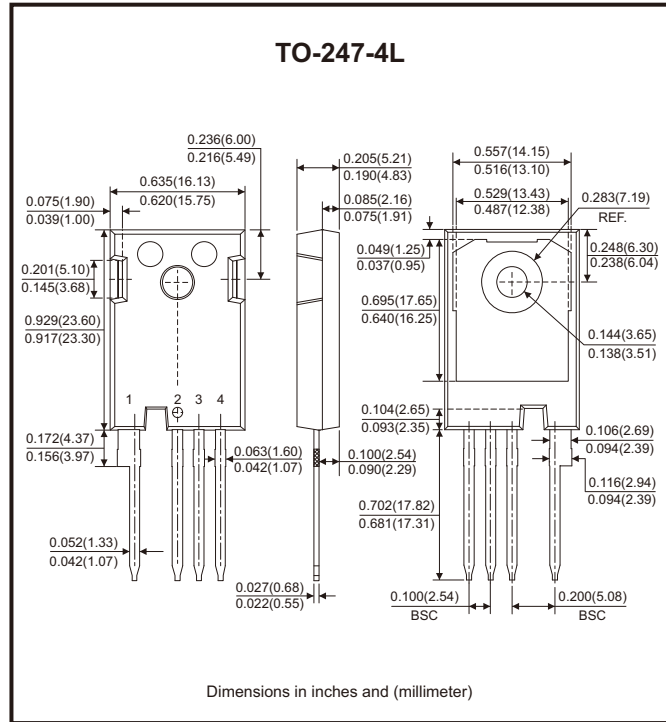
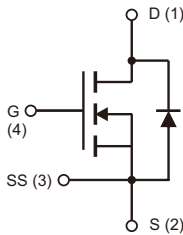
- Low on-resistance and high current density.
- Low capacitance for high frequency operation.
- Positive temperature coefficient device.
- Low impedance kelvin source pin-out.

### Mechanical data

- Case: TO-247-4L, molded plastic.
- Terminals: Solderable per MIL-STD-750, method 2026.
- Mounting position: Any.

### Circuit Diagram

G: Gate  
 S: Source  
 D: Drain



### Maximum Ratings (at TA=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{GS} = 0V, I_{bs} = 100\mu A$	$V_{DS, max}$	1200 V
Continuous drain current	$V_{GS} = 20V, T_c = 25^\circ C$	$I_D$	63 A
	$V_{GS} = 20V, T_c = 110^\circ C$	$I_D$	43.5 A
Pulse drain current	$t_{pw}$ limitation per Fig.15	$I_{D, pulse}$	227 A
Avalanche energy, single pulse	$V_{DD} = 100V, I_D = 12A$	$E_{AS}$	1875 mJ
Power dissipation	$T_c = 25^\circ C$	$P_D$	341 W
Recommend gate source voltage	Static, recommended DC operating values	$V_{GS, op}$	-5 to 20 V
Maximum gate source voltage	Transient operating limit (AC f > 1Hz, duty cycle < 1%)	$V_{GS, max}$	-10 to 25 V
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to 175	$^\circ C$
Soldering temperature	$T_L$	260	$^\circ C$
Mounting torque	M3 or 6-32 screw	$M_D$	1 Nm

### Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal resistance junction to case	$R_{\theta JC}$		0.44		$^\circ C/W$

## Electrical Characteristics (at $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS} = 0V, I_{DS} = 100\mu A$	1200			V	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{DS} = 40mA$	1.5	2.7	4.5	V	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 1200V, V_{GS} = 0V$		1	50	$\mu A$	
		$V_{DS} = 1200V, V_{GS} = 0V, T_J = 175^\circ\text{C}$		10	500		
Gate-source leakage current	$I_{GSS}$	$V_{GS} = 20V, V_{DS} = 0V$			250	nA	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 20V, I_{DS} = 30A$		40	52	m $\Omega$	
		$V_{GS} = 20V, I_{DS} = 30A, T_J = 175^\circ\text{C}$		75			
Transconductance	$g_{fs}$	$V_{DS} = 15V, I_{DS} = 30A$		15		S	
Input capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 800V, f = 1MHz, V_{AC} = 25mV$		3619		pF	
Output capacitance	$C_{oss}$			145			
Reverse transfer capacitance	$C_{rss}$			18			
Effective output capacitance, energy related	$C_{o(er)}$		$V_{GS} = 0V, V_{DS} = 0 \text{ to } 800V$		189		
Effective output capacitance, time related	$C_{o(tr)}$	$I_D = \text{const.}, V_{GS} = 0V, V_{DS} = 0 \text{ to } 800V$		264			
Turn on delay time	$t_{d(on)}$	$V_{DS} = 800V, V_{GS} = -4/+20V, I_D = 30A, R_L = 27\Omega, R_{G(ext)} = 2.7\Omega$		26		ns	
Rise time	$t_r$			50			
Turn off delay time	$t_{d(off)}$			7			
Fall time	$t_f$			11			
Coss stored energy	$E_{oss}$	$V_{GS} = 0V, V_{DS} = 800V, f = 1MHz, V_{AC} = 25mV$		60		$\mu J$	
Turn-on switching energy	$E_{on}$	$V_{DS} = 800V, V_{GS} = 0/20V, I_D = 40A, L = 350nH, R_{G(ext)} = 2.7\Omega$		326			
Turn-off switching energy	$E_{off}$			209			
Internal gate resistance	$R_{G(int.)}$	$f = 1MHz, V_{AC} = 25mV$		0.9		$\Omega$	
<b>Built-in SiC Diode Characteristics</b>							
Inverse diode forward voltage	$V_{SD}$	$V_{GS} = 0V, I_{SD} = 7.5A$		2.9		V	
Continuous diode forward current	$I_S$	$V_{GS} = 0V, T_C = 25^\circ\text{C}$		51		A	
Reverse recovery time	$t_{rr}$	$V_{GS} = 0V, I_{SD} = 30A, V_{DS} = 400V, di/dt = 300A/\mu s$		131		ns	
Reverse recovery charge	$Q_{rr}$				160		nC
Peak reverse recovery current	$I_{rrm}$				6.4		A

## Gate Charge Characteristics (at $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Value	Unit
Gate-source charge	$Q_{GS}$	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 30\text{A}$	68	nC
Gate-drain charge	$Q_{GD}$		66	
Total gate charge	$Q_G$		229	
Gate plateau voltage	$V_{pl}$		7.9	V

## Typical Rating and Characteristic Curves (CSMF40T040-HF)

Fig.1 - Forward Output Characteristics at  $T_J=25^\circ\text{C}$

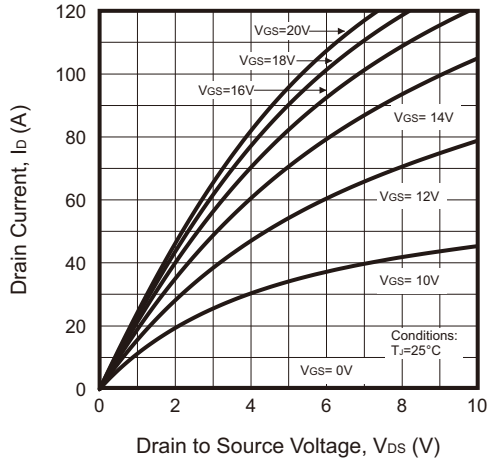


Fig.2 - Forward Output Characteristics at  $T_J=175^\circ\text{C}$

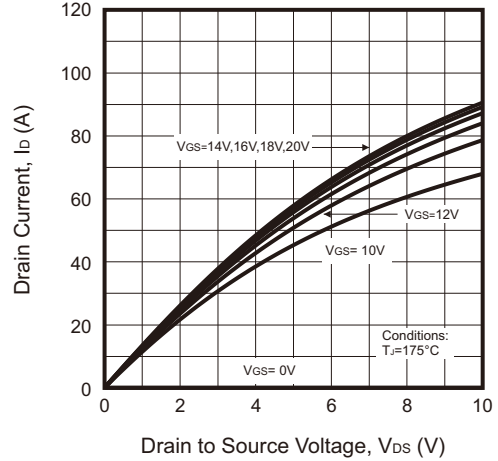


Fig.3 - On-Resistance vs. Drain Current for Various  $T_J$

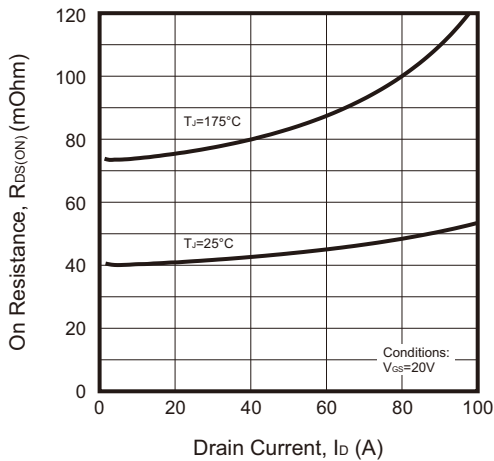


Fig.4 - Transfer Characteristics for Various  $T_J$

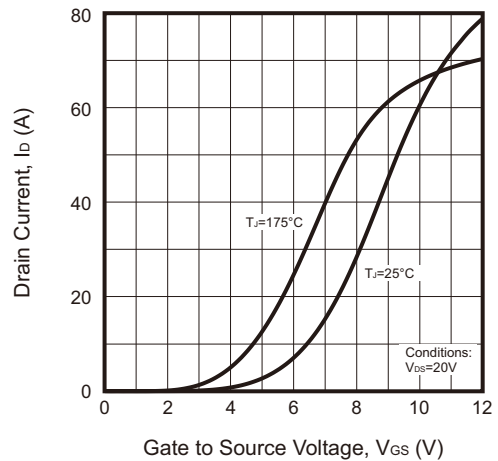


Fig.5 - On-Resistance vs. Gate Voltage for Various  $T_J$

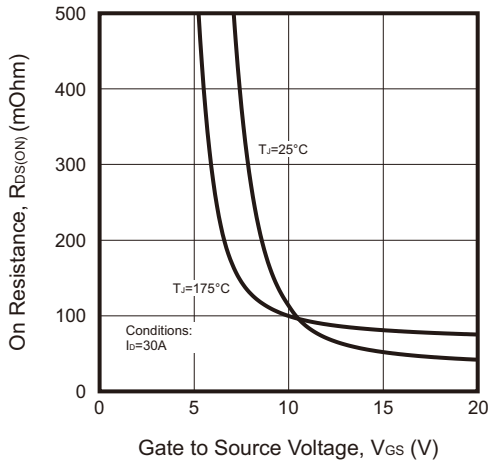
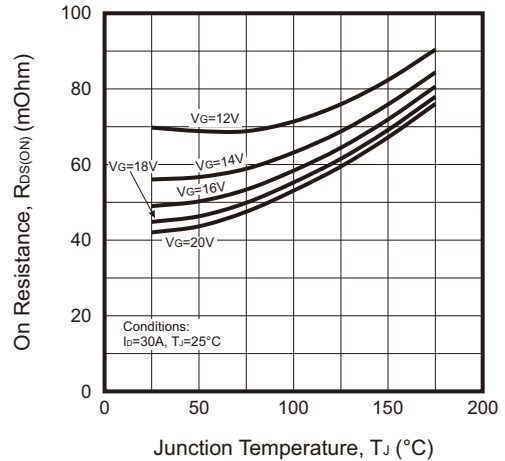


Fig.6 - On-Resistance vs. Temperature for Various Gate Voltage



## Typical Rating and Characteristic Curves (CSMF40T040-HF)

Fig.7 - Normalized On-Resistance vs. Temperature

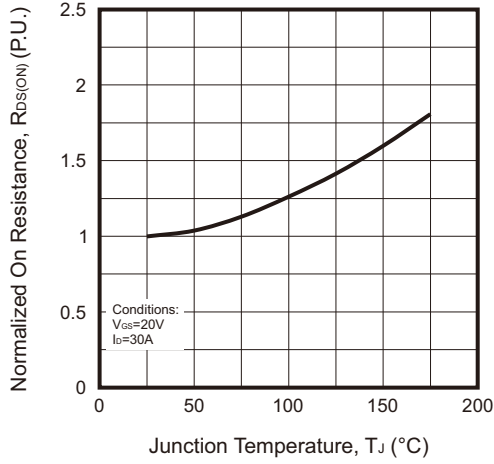


Fig.8 - Reverse Output Characteristics at  $T_J=25^\circ\text{C}$

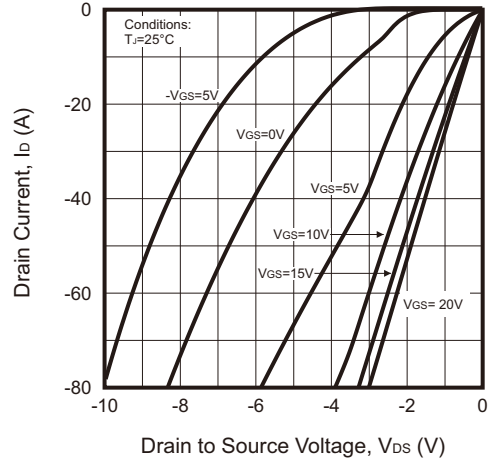


Fig.9 - Reverse Output Characteristics at  $T_J=175^\circ\text{C}$

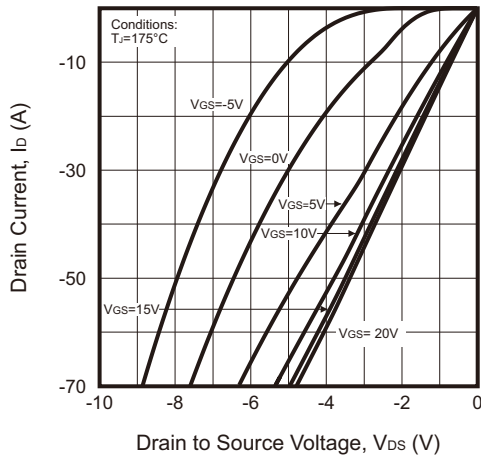


Fig.10 - Capacitance vs. Drain to Source Voltage

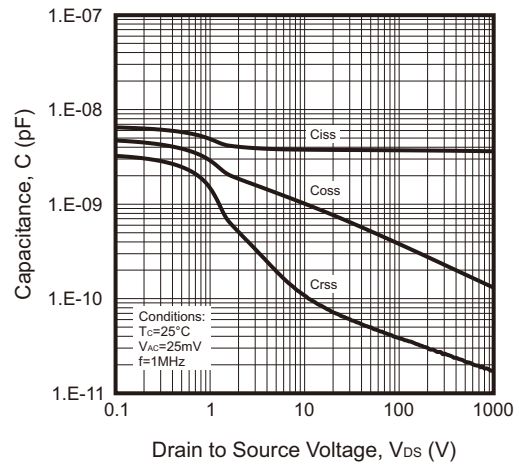


Fig.11 - Threshold Voltage vs. Temperature

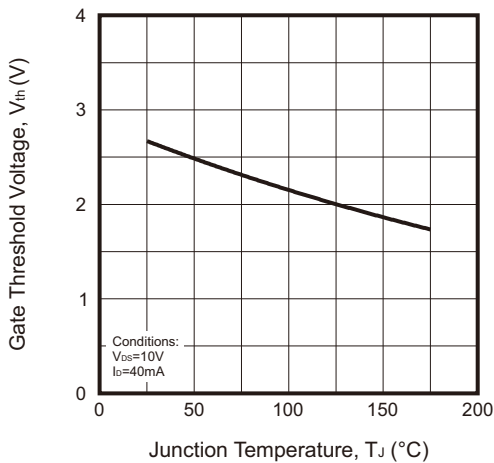
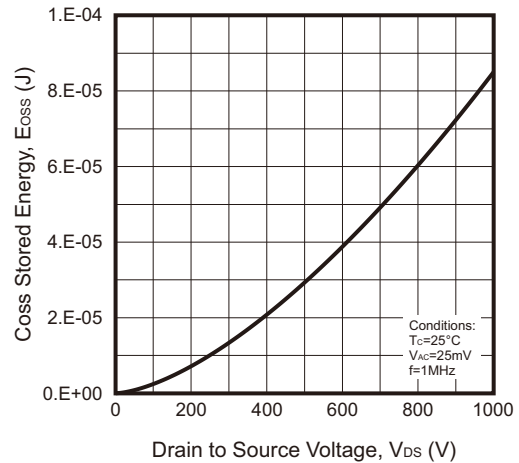


Fig.12 - Output Capacitor Stored Energy



## Typical Rating and Characteristic Curves (CSMFP4OT040-HF)

Fig.13 - Max. Power Dissipation Derating vs. Case Temperature

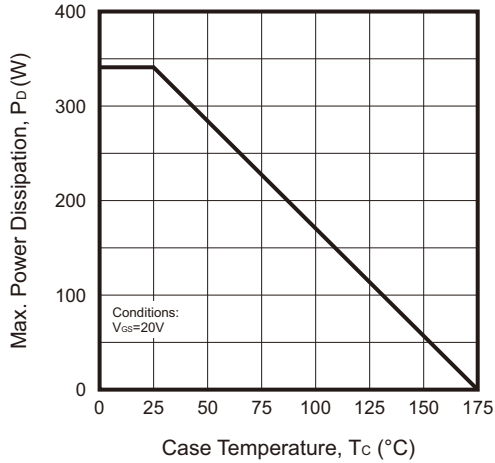


Fig.14 - Drain Current Derating vs. Case Temperature

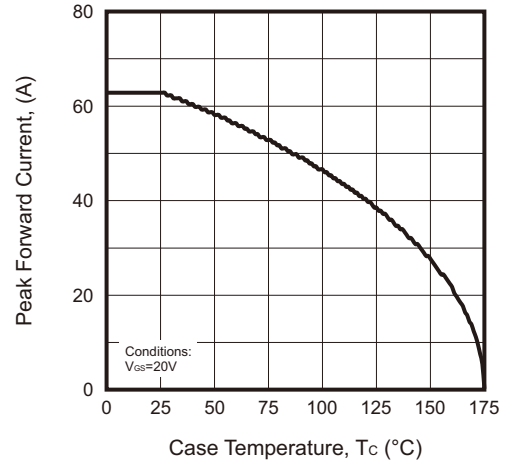


Fig.15 - Safe Operating Area

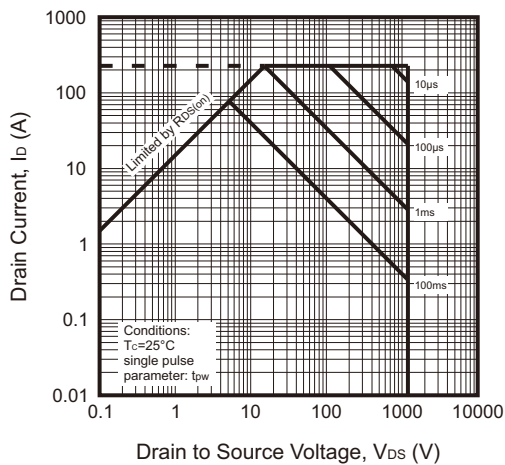


Fig.16 - Gate Charge Characteristics

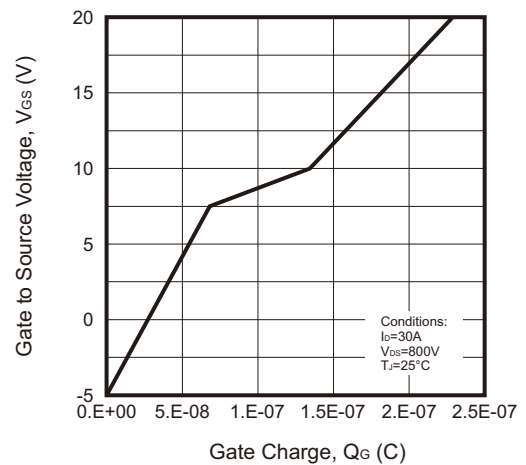


Fig.17 - Clamped Inductive Switching Energy vs. Drain Current

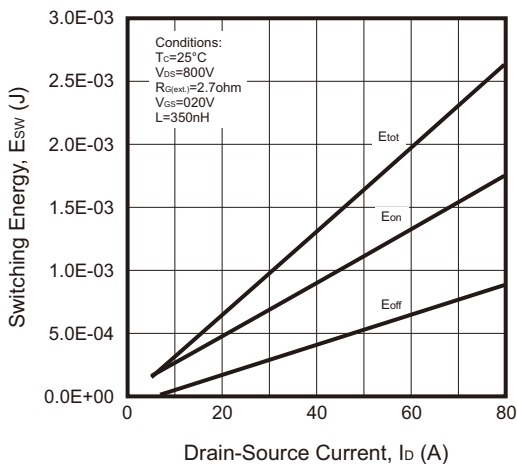
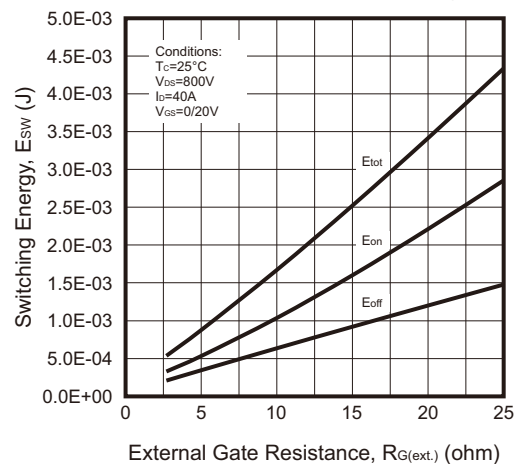
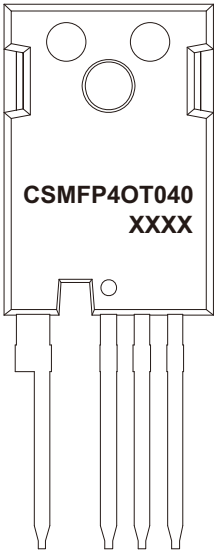


Fig.18 - Clamped Inductive Switching Energy vs. External Gate Resistor ( $R_{G(ext.)}$ )



## Marking Code

Part Number	Marking Code
CSMFP4OT040-HF	CSMFP4O040



XXXX = Control code

## Standard Packaging

Case Type	TUBE PACK
	TUBE (pcs)
TO-247-4L	30